



The 24th International Symposium on Laser Precision Microfabrication
Venue: Hirosaki Bunka Center, Hirosaki city, Aomori Prefecture, Japan

Website: <http://www.jlps.gr.jp/lpm/lpm2023/>

Sponsorship Opportunities

Welcome to join us at LPM2023!

The International Symposium on Laser Precision Microfabrication deals with science and technology of advanced laser materials processing covering precision microfabrication. The former LPMs have won the good reputation and popularity as the one of the most excellent international conferences in the world. LPM2023 will be held during June 13-16, 2023, in Hirosaki Bunka Center, Hirosaki city, Aomori Prefecture, Japan as "In-Person" conference.

LPM2023 is planned as a four-day event with a plenary session, oral and poster sessions, and two special sessions dealing with topical issues. The aim of this symposium is to provide a forum for discussion of fundamental aspects of laser-matter interaction, the state-of-the-art of laser materials processing, and topics for the next generation with fundamental scientists, end users and laser manufactures. We expect that LPM2023 would play an important role not only for understanding fundamental knowledge of laser materials processing but also forecasting future technologies to be developed and the future laser market.

We would like to encourage you to become a LPM sponsor. Please select your sponsorship category: Gold, Silver, Bronze Level Sponsorships and Catalog Display. For the details, please refer to the following pages. Thank you for your attention in advance.

Dr. Hiroyuki Niino, General Chair, LPM2023

Contact:

LPM2023 Secretariat, Japan Laser Processing Society
c/o Joining and Welding Research Institute, Osaka University,
11-1 Mihogaoka, Ibaraki, Osaka 567-0047, Japan
TEL/FAX: +81-6-6879-8642, E-mail: lpm2023@jlps.gr.jp

	GOLD Level	SILVER Level	BRONZE Level	Catalog Display
FEE (Tax included)	JPY 200000-	JPY 100000-	JPY 50000-	JPY 30000-
COMPANY MOVIE	YES	YES	YES	
ADVERTISEMENT	2 pages	1 page		
REGISTRATION	To be waived for one person (Banquet: Excluded)	To be waived for one person (Banquet: Excluded)		
CATALOG DISPLAY				Up to 200 sheets

1) LOGO (For all sponsors)

Company name and logo will be shown on the LPM2023 website and included "Technical Digest & Symposium Program" (Electric version). Suggested Logo size is 184x 60 pixel. Please send JPG file to the LPM2023 Secretariat at lpm2023@jlps.gr.jp

2) MOVIE (For GOLD, SILVER and BRONZE level sponsors)

Company movie will be uploaded on the LPM2023 website. Please send MP4 file (within 10 minutes, Language: In English) or YouTube URL to the LPM2023 Secretariat at lpm2023@jlps.gr.jp no later than May 15, 2023, JST.

3) ADVERTISEMENT (For GOLD and SILVER level sponsors)

A4 sized advertisement(s) will be included on the Technical Digest & Symposium Program (Electric version).

Advertisement Size: A4, Margin: 10 mm each., Language: English (Suggested)

Please send PDF file with embedded fonts by May 15, 2023, JST at lpm2023@jlps.gr.jp

4) CATALOG (Only for Catalog Display sponsors)

200 hardcopies of catalog should be sent to LPM2023 Secretariat by May 15, 2023.

Sending address:

LPM2023 Secretariat, Japan Laser Processing Society
c/o Joining and Welding Research Institute, Osaka University,
11-1 Mihogaoka, Ibaraki, Osaka 567-0047, Japan, TEL: +81-6-6879-8642

5) SYMPOSIUM REPORT (For all sponsors)

After the event, a symposium report will be sent to all sponsors. Please note that "Participants List" will not include any personal information; such as full names, e-mail addresses.)

SPONSORSHIP APPLICATION DUE DATE: APRIL 15, 2023

Please fill out the next page and send it to lpm2023@jlps.gr.jp

After receiving the application form, LPM2023 will send you the invoice.

PAYMENT DUE DATE: JUNE 30, 2023

To LPM2023 SECRETARIAT

E-mail: lpm2023@jips.gr.jp, FAX: +81-6-6879-8642

LPM2023 SPONSORSHIP APPLICATION FORM

DATE		For Secretariat use		
COMPANY NAME				
DEPARTMENT				
APPLICANT'S INFORMATION	FULL NAME:			
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SPONSORSHIP	CATEGORIES	FEE (JPY)	QUANTITY	SUB-TOTAL
	GOLD	200000		
	SILVER	100000		
	BRONZE	50000		
	CATALOG DISPLAY	30000		
	For WIRE-TRANSFER: HANDLING CHARGE JPY 4000			
	TOTAL AMOUNT			
URL FOR LINK				
<input type="checkbox"/> PAYMENT BY CREDIT CARD	<input type="checkbox"/> VISA <input type="checkbox"/> MASTER CARD			
	CARD NUMBER:			
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<input type="checkbox"/> PAYMENT BY WIRE-TRANSEER	Bank name (Bank code#) Sumitomo Mitsui Banking Corporation (#0009)			
	Branch (Branch code#) Minami Senri (#189)			
	SWIFT Code: SMBCJPJT			
	Account name: Itpan Shadan Hojin Laser Kako Gatkai			
	Account type: Regular (Futsu)			
	Account Number: 1159822			
	Bank address: 1-2-D9-101, Tsukumodai, Suita, Osaka 565-0862, Japan			
	Bank phone #: +81-6-6833-1911			
Note: 1) Please make sure to add ¥4000 bank handling charge.				
2) Please bear your local bank's handling charge by yourself.				

Personal information will be used only for administrative procedures and will not be used elsewhere.